

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|--|---|------------------|
| 1 | 6010 | solder near3 (melting adj point or melting near3 temperature) | USPAT; US-PGPUB | 2004/08/02 11:17 |
| 2 | 1024 | (solder near3 (melting adj point or melting near3 temperature)) and optical | USPAT; US-PGPUB | 2004/08/02 11:16 |
| 3 | 844 | ((solder near3 (melting adj point or melting near3 temperature)) and optical) and (bond bonding bonded) | USPAT; US-PGPUB | 2004/08/02 11:16 |
| 4 | 50221 | (lower higher greater less) near5 (melting adj point or melting near3 temperature) | USPAT; US-PGPUB | 2004/08/02 11:18 |
| 5 | 386 | ((solder near3 (melting adj point or melting near3 temperature)) and optical) and (bond bonding bonded)) and ((lower higher greater less) near5 (melting adj point or melting near3 temperature)) | USPAT; US-PGPUB | 2004/08/02 11:23 |
| 6 | 213 | ((solder near3 (melting adj point or melting near3 temperature)) and optical) and (bond bonding bonded)) and ((lower higher greater less) near5 (melting adj point or melting near3 temperature))) and @pd<20020620 | USPAT; US-PGPUB | 2004/08/02 11:24 |
| 8 | 31 | (US-6046909-\$ or US-6005777-\$ or US-5956415-\$ or US-6492699-\$ or US-6052287-\$ or US-6495895-\$ or US-6515269-\$ or US-6512219-\$ or US-6627864-\$ or US-6674159-\$ or US-5087964-\$ or US-5122861-\$ or US-5196919-\$ or US-5612549-\$ or US-6384473-\$ or US-6072232-\$ or US-6350113-\$ or US-6428650-\$ or US-5297333-\$ or US-6603183-\$ or US-5898215-\$ or US-5449908-\$ or US-5612256-\$ or US-5936848-\$ or US-5798557-\$ or US-6252229-\$).did. or (US-6686653-\$ or US-4178529-\$ or US-6122009-\$).did. or (US-20010028557-\$ or US-20020023765-\$ or US-20020027265-\$ or US-20030222333-\$ or US-20030146384-\$).did. or (EP-1289281-\$).did. or (JP-11354769-\$).did. or (WO-200165836-\$).did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2004/08/02 12:45 |
| 9 | 21 | ((US-6603183-\$) or US-6384473-\$ or US-5087964-\$ or US-5798557-\$ or US-5196919-\$ or US-5122861-\$ or US-5612549-\$ or US-5898215-\$ or US-5689106-\$ or US-6072232-\$ or US-6005777-\$ or US-5936848-\$ or US-6046909-\$ or US-6052287-\$ or US-6674159-\$ or US-6627864-\$ or US-6603183-\$ or US-6515269-\$ or US-6512219-\$ or US-6495895-\$ or US-6492699-\$).did. or (US-20010028557-\$).did. or (JP-11354769-\$).did. | USPAT; US-PGPUB; JPO | 2004/08/02 12:45 |
| 10 | 20 | (US-5122861-\$ or US-4590539-\$ or US-4841100-\$ or US-6384473-\$ or US-5640207-\$ or US-4622580-\$ or US-5087964-\$ or US-5903706-\$ or US-6541837-\$ or US-6072232-\$ or US-5689106-\$ or US-5612549-\$ or US-5319521-\$ or US-5314742-\$ or US-5196919-\$ or US-5223741-\$ or US-5296724-\$ or US-5895233-\$ or US-3934074-\$).did. or (US-20030128291-\$ or US-20030146384-\$).did. or (EP-1289281-\$).did. or (JP-11354769-\$).did. or (WO-200165836-\$).did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2004/08/02 12:45 |
| 11 | 21 | (US-5956415-\$ or US-5612256-\$ or US-5449908-\$ or US-5297333-\$ or US-6072232-\$ or US-6046909-\$ or US-6674159-\$ or US-6627864-\$ or US-6515269-\$ or US-6512219-\$ or US-6492699-\$ or US-6052287-\$ or US-6005777-\$ or US-5936848-\$ or US-5898215-\$ or US-6495895-\$ or US-5612549-\$ or US-5196919-\$ or US-5122861-\$ or US-5087964-\$).did. or (US-20010028557-\$).did. or (EP-1289281-\$).did. or (JP-11354769-\$).did. or (WO-200165836-\$).did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2004/08/02 12:45 |
| 12 | 276 | ((257/432,433,434,436,680,703,704,710,723) or (250/338.1,338.4)).CCLS. and @pd>20040310 | USPAT; US-PGPUB | 2004/08/02 12:46 |
| 13 | 20 | (solid-state-imaging solid-state adj imaging solid-state adj imager) and resin and @pd>20040310 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/02 12:47 |
| 14 | 5 | imager WITH circuit adj board and @pd>20040310 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/02 12:47 |
| 15 | 41 | flip-chip and (ccd optical adj sensor) and @pd>20040310 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/02 12:47 |
| 16 | 13 | (flip-chip and (ccd optical adj sensor) and @pd>20040310) and infrared | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/02 12:47 |

| | | | | |
|----|----|--|---|------------------|
| 17 | 11 | 5,895,233 and @pd>20040310 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/02 12:48 |
| 18 | 3 | (5,895,233 and @pd>20040310) and infrared | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/02 12:48 |
| 19 | 3 | (5,895,233 and @pd>20040310) and infrared and solder | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/02 12:48 |